



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Parameter	Rating	Units
Blocking Voltage	60	V _P
Load Current	4	A _{DC}
On-Resistance (max)	0.09	Ω

Features

- Handle Load Currents Up to 4A_{DC}
- 2500V_{rms} Input/Output Isolation
- Power SIP Package
- High Reliability
- Low Drive Power Requirements
- Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- Flammability Rating UL 94 V-0

Applications

- Industrial Controls
- Motor Control
- Robotics
- Medical Equipment—Patient/Equipment Isolation
- Instrumentation
- Multiplexers
- Data Acquisition
- Electronic Switching
- I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- IC Equipment
- Home Appliances

Description

IXYS Integrated Circuits Division and IXYS have combined to bring OptoMOS® technology, reliability, and compact size to a new family of high power solid state relays. The CPC1706, a DC-switching, normally open (1-Form-A) Solid State Relay, is part of that family.

Employing optically coupled MOSFET technology, the CPC1706 provides 2500V_{rms} of input to output isolation. The relay output is constructed with efficient MOSFET switches that use IXYS Integrated Circuits Division's patented OptoMOS architecture. The input, a highly efficient infrared LED, controls the optically coupled output.

The combination of low on-resistance and high load current handling capability makes this relay suitable for a variety of high performance switching applications.

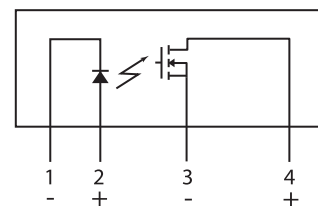
Approvals

- UL 508 Certified Component: File E69938
- CSA Certified Component: Certificate 1172007

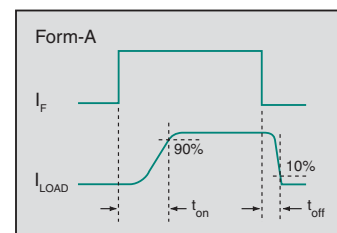
Ordering Information

Part #	Description
CPC1706Y	4-Pin (8-Pin Body) Power SIP Package (25 per tube)

Pin Configuration



Switching Characteristics of Normally Open Devices



Absolute Maximum Ratings @ 25°C

Parameter	Min	Max	Units
Blocking Voltage	-	60	V _P
Reverse Input Voltage	-	5	V
Input control Current	-	50	mA
Peak (10ms)	-	1	A
Input Power Dissipation ¹	-	150	mW
Total Power Dissipation ²	-	1600	mW
Isolation Voltage, Input to Output	-	2500	V _{rms}
Operational Temperature	-40	+85	°C
Storage Temperature	-40	+125	°C

¹ Derate linearly 3.33 mW / °C

² Derate linearly 16.667 mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

Electrical Characteristics @ 25°C (Unless Otherwise Noted)

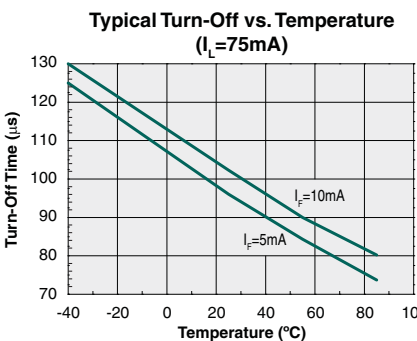
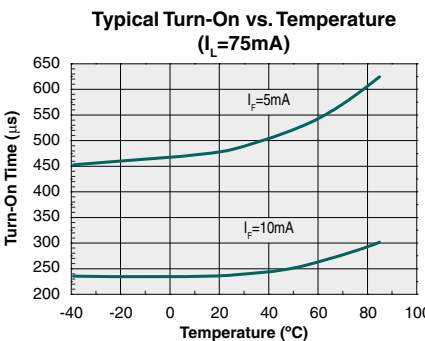
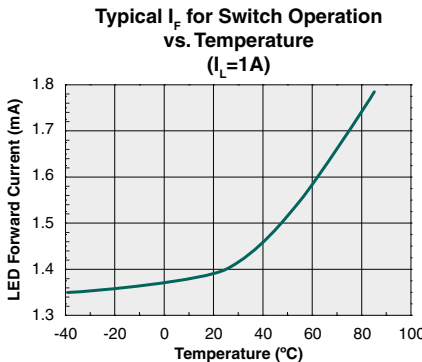
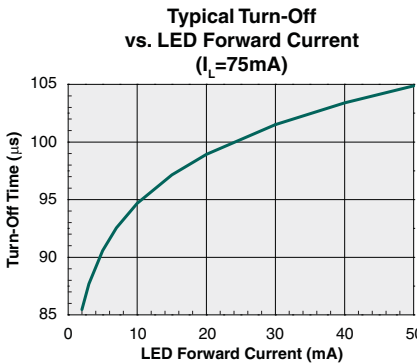
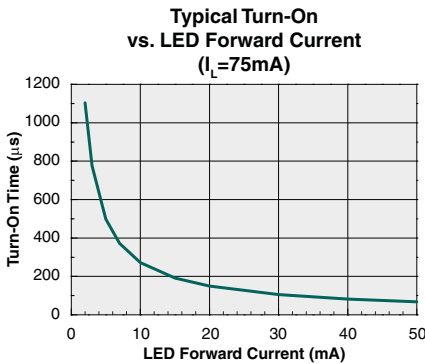
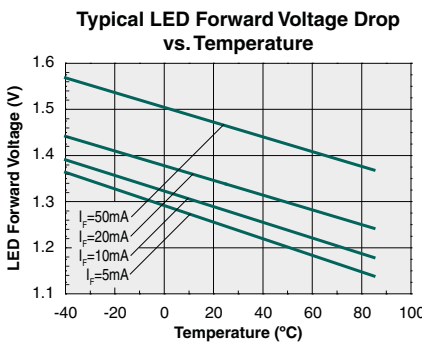
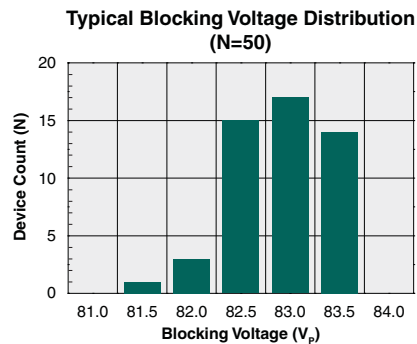
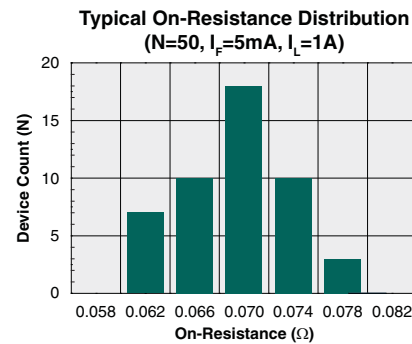
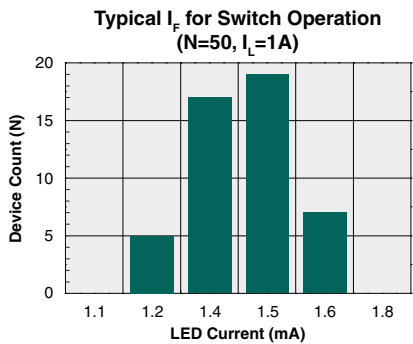
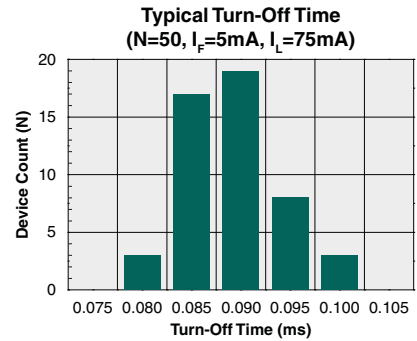
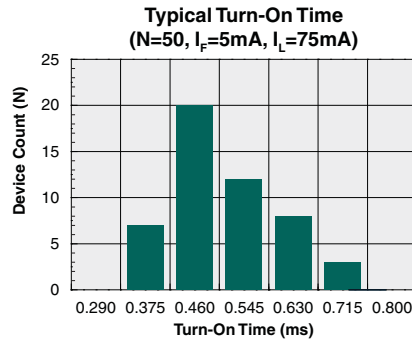
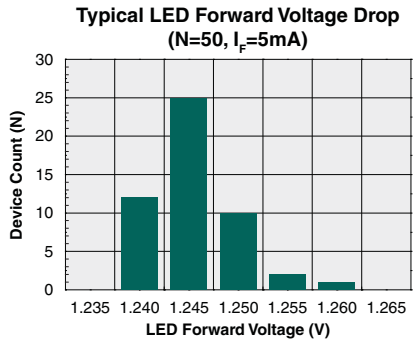
Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Load Current, Continuous	I _F =5mA, Free air	I _L	-	-	4	A _{DC}
Peak Load Current	I _F =5mA, t=10ms	I _{LPK}	-	-	9	A
On-Resistance ¹	I _F =5mA, I _L =1A	R _{ON}	-	0.07	0.09	Ω
Off-State Leakage Current	I _F =0mA, V _L =60V _P	I _{LEAK}	-	-	1	μA
Switching Speeds						
Turn-On	I _F =5mA, V _L =10V	t _{on}	-	0.5	5	ms
Turn-Off		t _{off}	-	0.085	2	
Output Capacitance	I _F =0mA, V _L =50V, f=1MHz	C _{OUT}	-	75	-	pF
Input Characteristics						
Input Control Current to Activate	I _L =1A	I _F	-	1.4	5	mA
Input Control Current to Deactivate	-	I _F	0.4	-	-	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.4	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μA
Input/Output Characteristics						
Capacitance Input-to-Output	V _{IO} =0V, f=1MHz	C _{IO}	-	2	-	pF

¹ Measurement taken within 1 second of on-time.

Thermal Characteristics

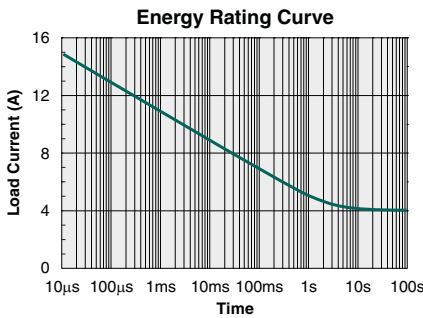
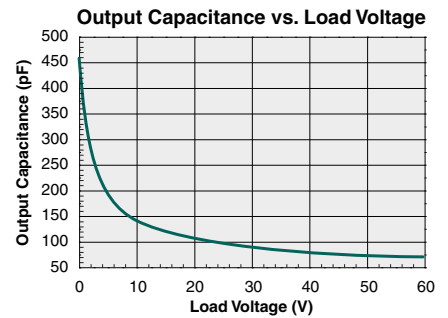
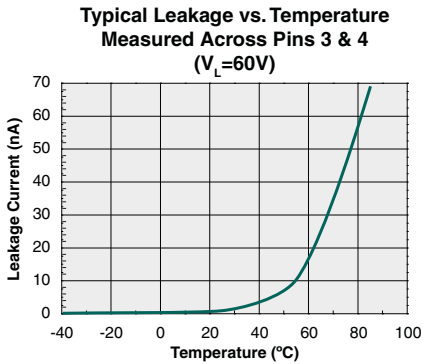
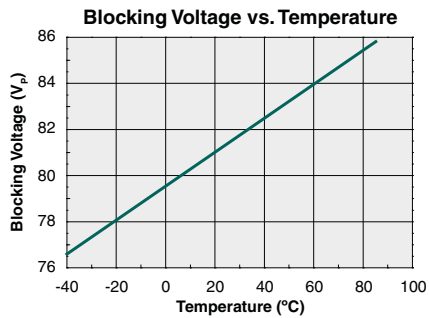
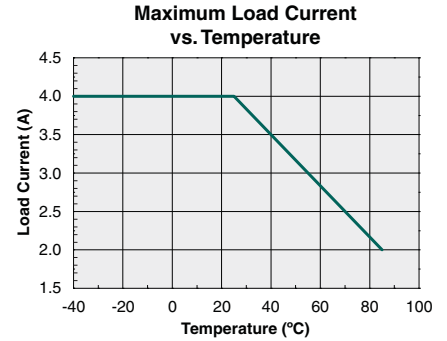
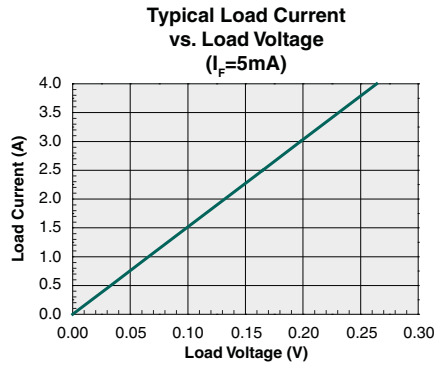
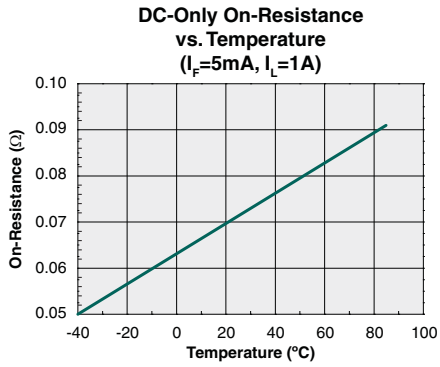
Parameter	Conditions	Symbol	Min	Typ	Max	Units
Thermal Impedance (junction to case)	-	θ _{JC}	-	1.5	-	°C/W

PERFORMANCE DATA @25°C (Unless Otherwise Noted)*



* The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

PERFORMANCE DATA @25°C (Unless Otherwise Noted)*



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Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, IPC/JEDEC J-STD-020, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a Moisture Sensitivity Level (MSL) classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard IPC/JEDEC J-STD-033.

Device	Moisture Sensitivity Level (MSL) Classification
CPC1706Y	MSL 1

ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Soldering Profile

Provided in the table below is the Classification Temperature (T_c) of this product and the maximum dwell time the body temperature of this device may be above ($T_c - 5$)°C. The classification temperature sets the Maximum Body Temperature allowed for this device during lead-free reflow processes. For through hole devices, and any other processes, the guidelines of **J-STD-020** must be observed.

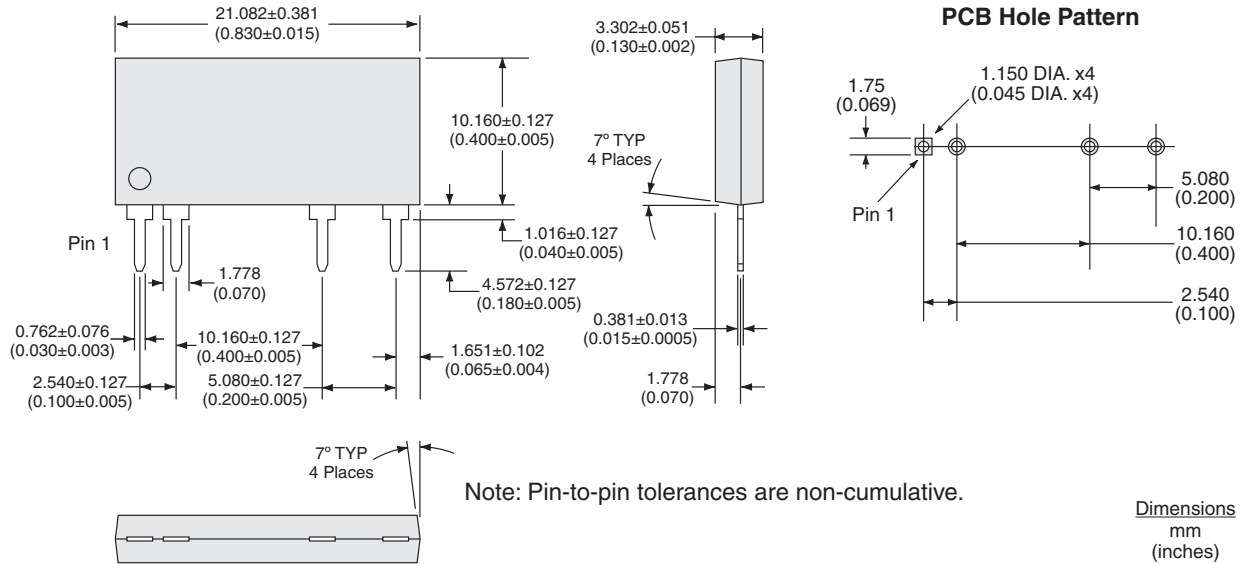
Device	Classification Temperature (T_c)	Dwell Time (t_p)	Max Reflow Cycles
CPC1706Y	245°C	30 seconds	1

Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include, but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to flux or solvents that are Chlorine- or Fluorine-based. Cleaning methods that employ ultrasonic energy should not be used.



MECHANICAL DIMENSIONS



For additional information please visit our website at: www.ixysic.com

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Specification: DS-CPC1706-R04
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